

ABSTRACT

An object of the present invention is to provide an electroconductive adhesive composition which has excellent thermal conductivity and which, even when repeatedly
5 undergoing fluctuations in temperature, is less apt to cause adherend separation. The present invention relates to an electroconductive adhesive composition which contains: an electroconductive filler (A) containing metal particles (a1) having an average particle diameter of 0.5-10 μm and silver particles (a2) having an average particle diameter of 10-200 nm; and particles (B) of a thermoplastic resin which is solid at 25°C.